



IT-8615G

IT-8615G- Next Generation High DK Halogen free product for

- 4 G LTE Base Stations
- 5 G Base Stations & mm wave applications
- Antenna applications

Features

- Thermoset system with 200 °C Tg
- Very low loss ~0.0035 at 10 GHz.
- Halogen Free
- Excellent dimensional stability
- Very stable DK/Df with Temperature
- Ability to use very low profile Copper for reduced insertion loss.
- Highly suitable for Hybrids
- Ability to make high layer count boards
- Full prepreg offering

Data sheet - IT-8615G

Property		Units	IT-8615G	
		Units	DK-6.15	
THERMAL	Thickness		0.504(20 mils)	
	Glass Transition Temp (Tg)	DMA	°C	215
		DSC	°C	203
		TMA	°C	201
	Time to Delam (T300)	With Cu	min.	> 60
	Solder Float		min.	> 60
	Solder Dip (PCT@1 hour and 121°C)		min.	> 60
	Thermal Decomposition Temp (5wt%)		°C	434
	CTE: RT-150°C	X-axis	ppm/°C	15.1
	CTE: RT-150°C	Y-axis	ppm/°C	14.0
	CTE:α1	Z - axis	ppm/°C	49
	CTE:α2	Z - axis	ppm/°C	220
CTE	Z - axis	%	1.90	
ELECTRICAL	Thickness		0.504(20 mils)	
	Dielectric Constant (Dk)	@2GHz		6.15
		@3GHz		6.15
		@5GHz		6.15
		@10GHz		6.15
	Dielectric Factor (Df)	@2GHz		0.0035
		@3GHz		0.0036
		@5GHz		0.0037
@10GHz			0.0037	
PHYSICAL	Water Absorption		0.18	
	Peel Strength	1 oz (RTF)	lb/in	>4.0
	Flammability	-	Second	V0
	Thermal Conductivity		W/(mx ° C)	0.62
	Elastic modulus	X-axis	GPa	18.10
Y-axis		GPa	17.60	